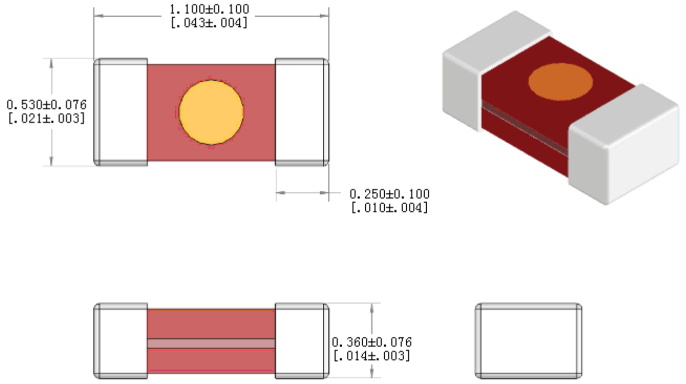
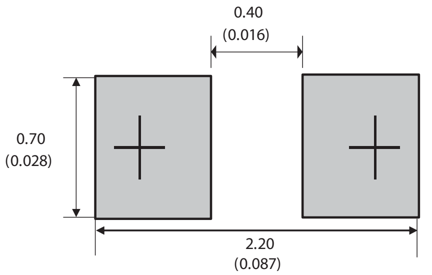
Dimensions - mm (in)



Recommended Pad Layout - mm (in)

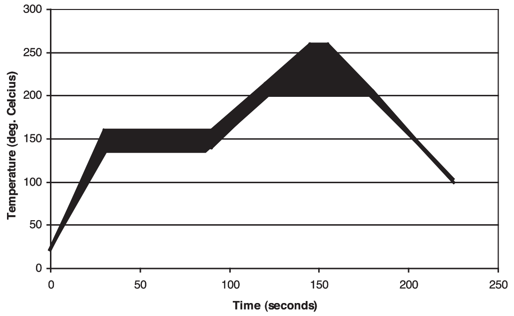


Environmental Specifications:

- High Temperature Exposure: MIL-STD-202 Method 108
- Temperature Cycling: 1000 Air to Air cycles -40°C to +125°C JESD22 Method JA-104
- Moisture Resistance Test: MIL-STD-202 Method 106G, 10 cycles
- Biased Humidity: MIL-STD-202 Method 103, 1,000hours +85°C, 85%RH
- Thermal Shock: MIL-STD-202, Method 107G Air-to-Air -55°C to +125°C, 10 cycles
- Vibration Test and Mechanical Shock Test: MIL-STD-202 Method 204 and Method 213
- Resistance to Solvent: MIL-STD-202 Method 215
- Operating and Storage Temperature Range: -55°C to +125°C

Soldering Recommendations

- Compatible with lead and lead-free solder reflow processes
- Peak reflow temperatures and durations:
  - IR Reflow = 260°C max for 10 sec. max
  - Wave Solder = 260°C max. for 10 sec. max
- Recommended IR Reflow Profile:



Eaton
Electronics Division
1000 Eaton Boulevard
Cleveland, OH 44122
United States
www.eaton.com/electronics

Publication No. 4083 BU-SB10613
June 2017

Powering Business Worldwide